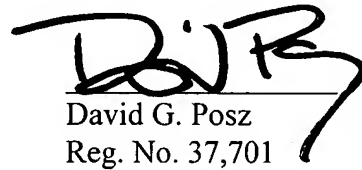


REMARKS

Examination of the present application in view of the above amendment is respectfully requested.

The above amendment was made to conform the U.S. specification to the basic Japanese specification by correcting a minor typographical error. Applicant submits that this amendment does not introduce any new subject matter.

Respectfully submitted,


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MARKED-UP VERSION OF THE AMENDED SPECIFICATION

Please replace the paragraph beginning at page 21 line 26 with the following:

In order to confirm the effect, different samples (magnetic sensor chips) on which different types of films are formed for the organic film 36 were prepared and experiments were conducted to investigate how cracking would occur. Specifically, for the organic film 36, three samples with different types of films as listed in Table 2, that is, a 0.5 μm thick polyimide film, a 1 μm thick polyimide film and a 0.7 μm thick resist film, were prepared. The chip was fixed to the Cu lead frame 50 through the Ag paste layer 52 by heat treatment (180°C, 60 min), followed by the step of cooling down to a room temperature and further down to -40°C [-140°C] to measure the temperature at which cracking began to occur. The measurement results are shown in Table 2 as “Cracking temperature.”